

REMARKS

Claims 17-20 remain allowed. Claims 1-16 & 21 were rejected under 35 U.S.C. 112, first paragraph. Examiner asserted that claim 1 has been amended to recite the formation of a metal layer on the plate, but the originally-filed specification does not support the formation of any and all metal layers on the substrate but only those facilitating separation of the plate and the organic resin.

In response, Applicants respectfully point out that the above amendment to claim 1 actually can be supported by the specification, at least because

1) the plate is not the substrate, as seen from claim 1 recited and marked below, while the metal layer is formed on the plate but not on the substrate,

“Claim 1. A manufacturing method ..., comprising the following steps:

providing a substrate;

forming a reflective layer on the substrate;

applying a radiation-setting resin on the reflective layer;

providing a plate having a flat surface;

forming a metal layer on the plate;”

2) [0017]/line 1 of the specification describes “a poorly-adhesive **metal layer** can be formed on the **plate**”, and

3) [0042] describes “a poorly-adhesive **metal layer** 220 is formed on a **plate** 204” (lines 1-2) and mentions in lines 5-7 that the material of the poorly-adhesive **metal layer** 220 can be selected from **metal materials** including gold, silver, aluminum, chromium, platinum, nickel, copper, palladium, silicon and the alloy thereof.

Accordingly, Applicants submit that the above amendment to claim 1 is supported by the originally-filed specification, and therefore respectfully request withdrawal of the rejections to claims 1-16 & 21 under 35 U.S.C. 112.

CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-16 & 21 of the present application are in proper condition for allowance like claims 17-20 are. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
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Date: December 28, 2009

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